

Application No.: 10/763,859  
Attorney Docket: AMKOR-053G

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicants:	Tae Heon Lee	)	Confirmation No.	8528
		)		
Serial No.:	10/763,859	)	Art Unit:	2814
		)		
Filed:	01/23/2004	)	Examiner:	Cao, Phat X.
		)		
For:	Semiconductor Package Having	)		
	Reduced Thickness	)		

**AMENDMENT AFTER ALLOWANCE UNDER 37 C.F.R. §1.312**

Mail Stop Issue Fee  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir/Madam:

A Notice of Allowance was mailed by the U.S. Patent and Trademark Office in relation to the above-identified patent application on May 4, 2006. Since Applicant has not yet paid the issue fee in relation to the present application, in accordance with the provisions of 37 C.F.R. §1.312(a), Applicant respectfully requests that the application be amended as follows:

*Amendments to the Specification* begin on page 2 of this paper; and

*Remarks* begin on page 3 of this paper.